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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE UNITED STATES PATENT	(2) toota
In re PATENT Application of	7-16-02
Akihiko ISHIBASHI et al) Art Unit Group: 2812
JUL 1 0 2007 Janese Priority Application No. 11-299640) Examiner: Savitri Mulpuri
Ispanese Priority Date: October 21, 1999	
For: METHOD OF FABRICATING NITRIDE) Date: July 10, 2002
SEMICONDUCTOR DEVICE	
	ROOT

PRELIMINARY AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Please preliminarily amend the subject application as follows:

IN THE CLAIM:

Please note that the amended claims are presented below in their amended form. It is further as an Attachment to the Amendment whereby the amendments to the specification is outlined using the conventional method of bracketing and underlining.

13. (AMENDED) A method of fabricating a nitride semiconductor device by a vapor deposition method comprising:

a step of growing, on a substrate, a first nitride semiconductor layer including magnesium under a first growth ambient pressure; and

a step of growing a second nitride semiconductor layer, which is adjacent to said first nitride semiconductor layer and does not include aluminum and magnesium, under a second growth ambient pressure,

wherein said first growth ambient pressure is lower than said second growth ambient pressure, and is lower than the atmospheric pressure